

Defect localization, characterization and reliability model development for microsystems-enabled photovoltaics

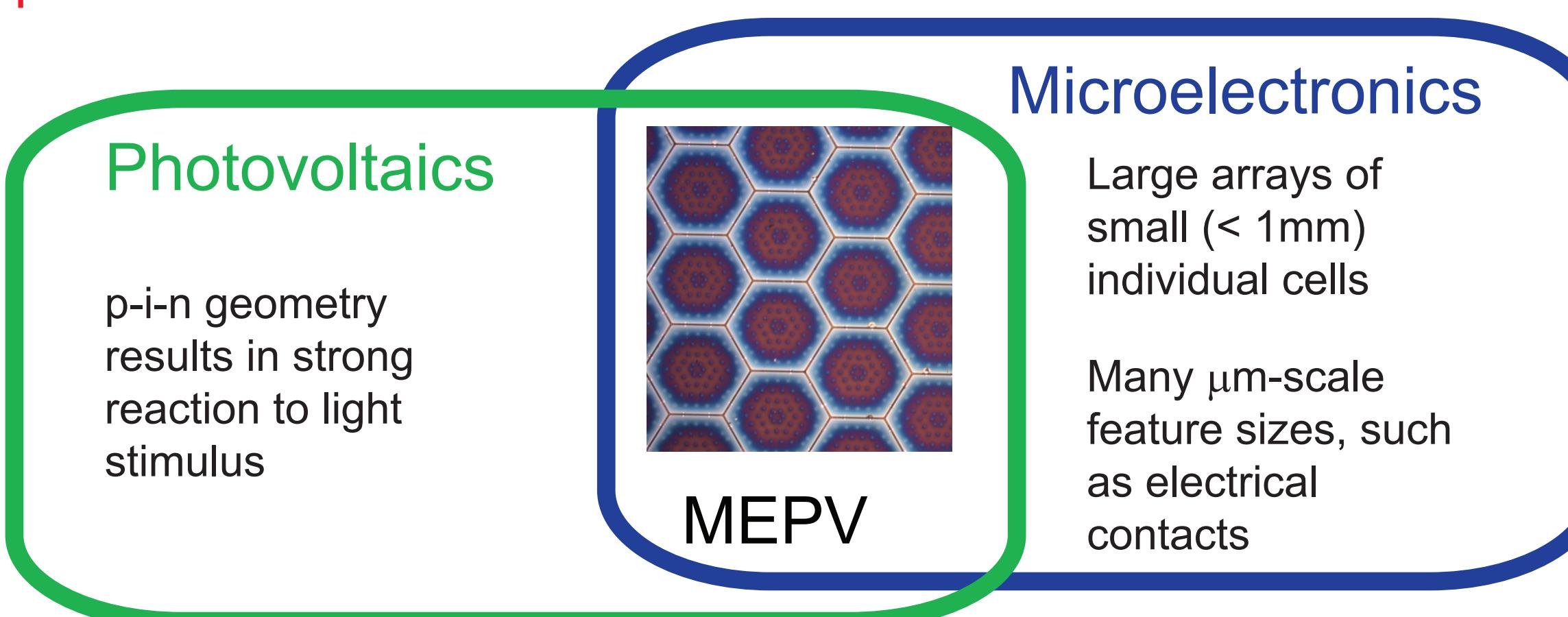
Benjamin B. Yang, Jose L. Cruz-Campa, Gaddi S. Haase, Edward I. Cole Jr., Paiboon Tangyunyong, Murat Okandan, Gregory N. Nielson

Introduction



Microsystems-enabled photovoltaics (MEPV) is a microfabricated photovoltaic (PV) device.

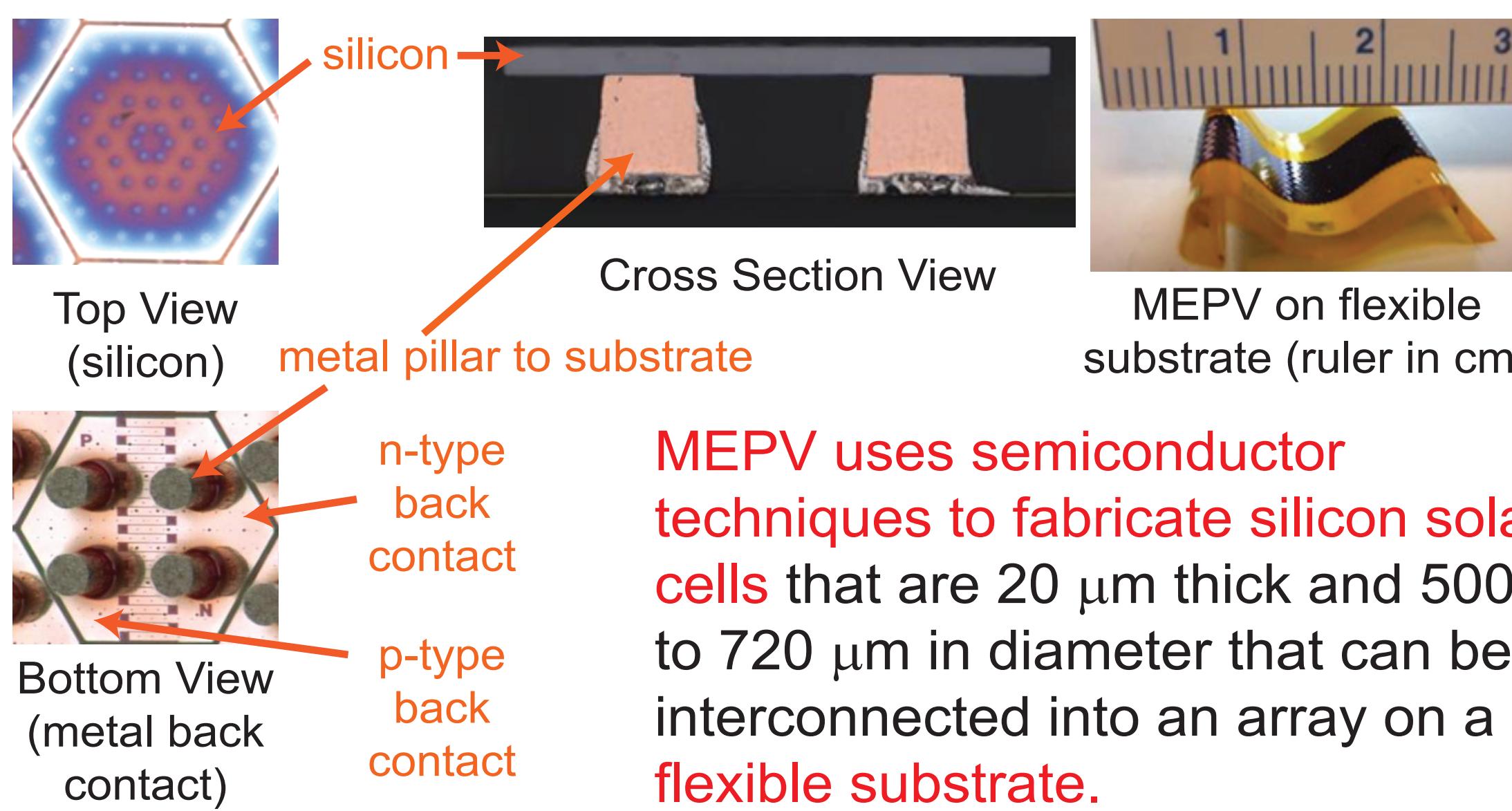
MEPV has unique **failure analysis** and **reliability** opportunities because it lies at the **intersection of microelectronics and photovoltaics**.



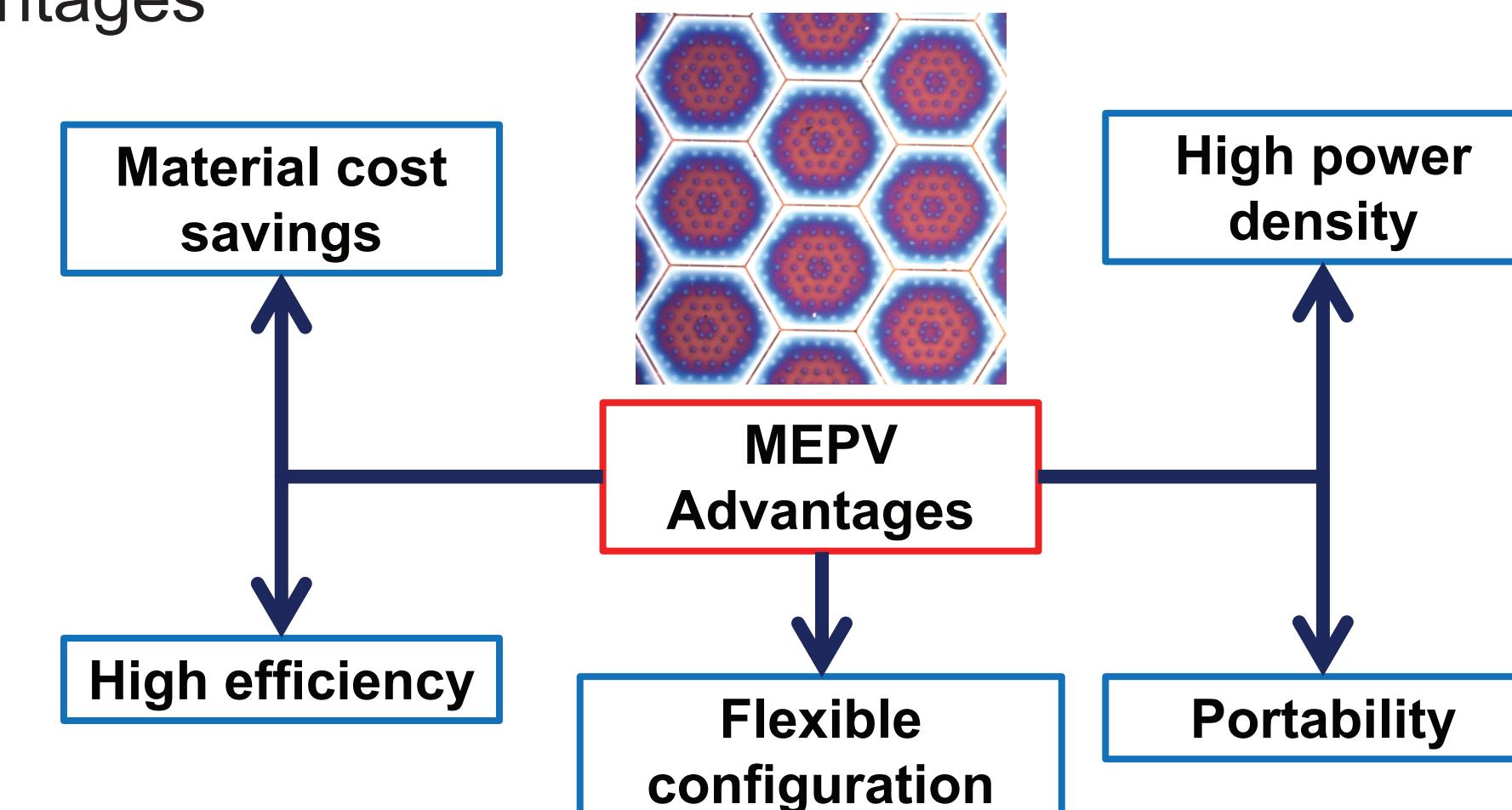
In this project, we successfully adapted failure analysis techniques for microelectronics for defect localization in MEPV.

These techniques form a set of tools for building the first reliability model for MEPV, as demonstrated a case study establishing MEPV's robustness to reverse bias stress.

MEPV Overview

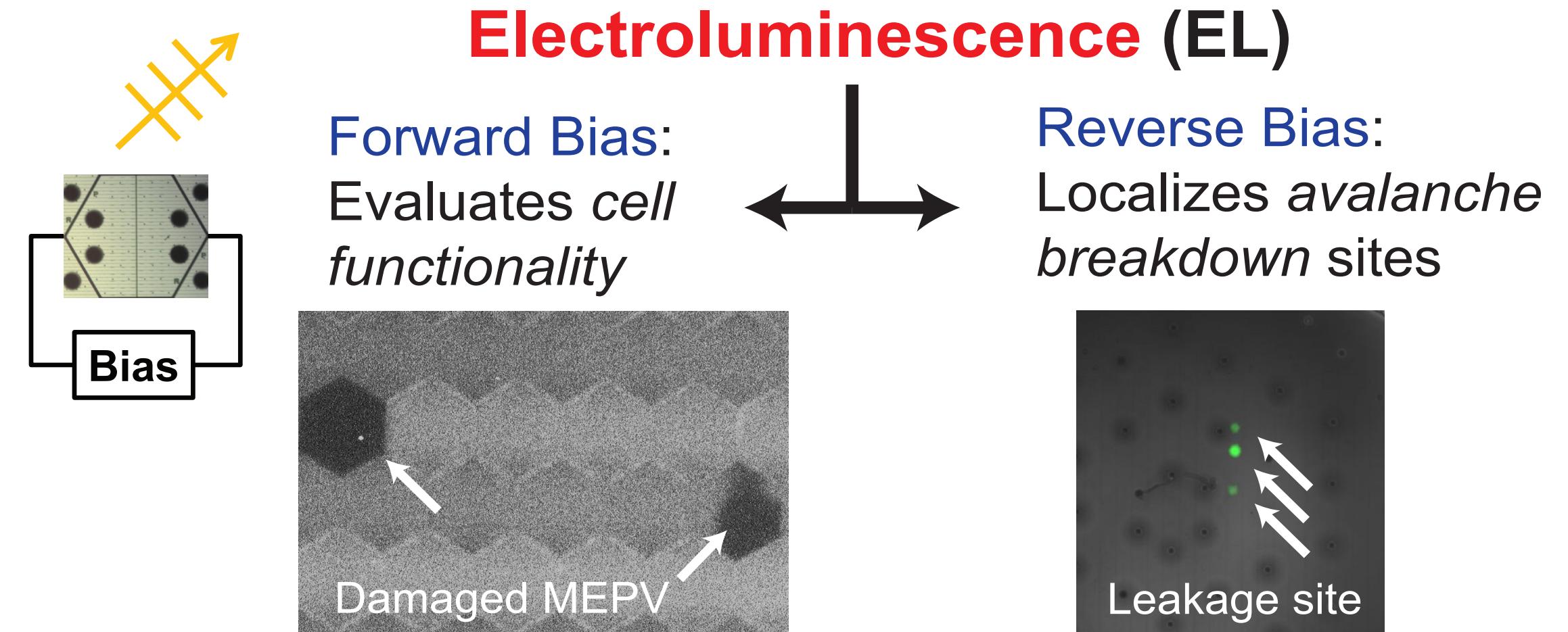


Scaling effects of the MEPV approach leads to several advantages



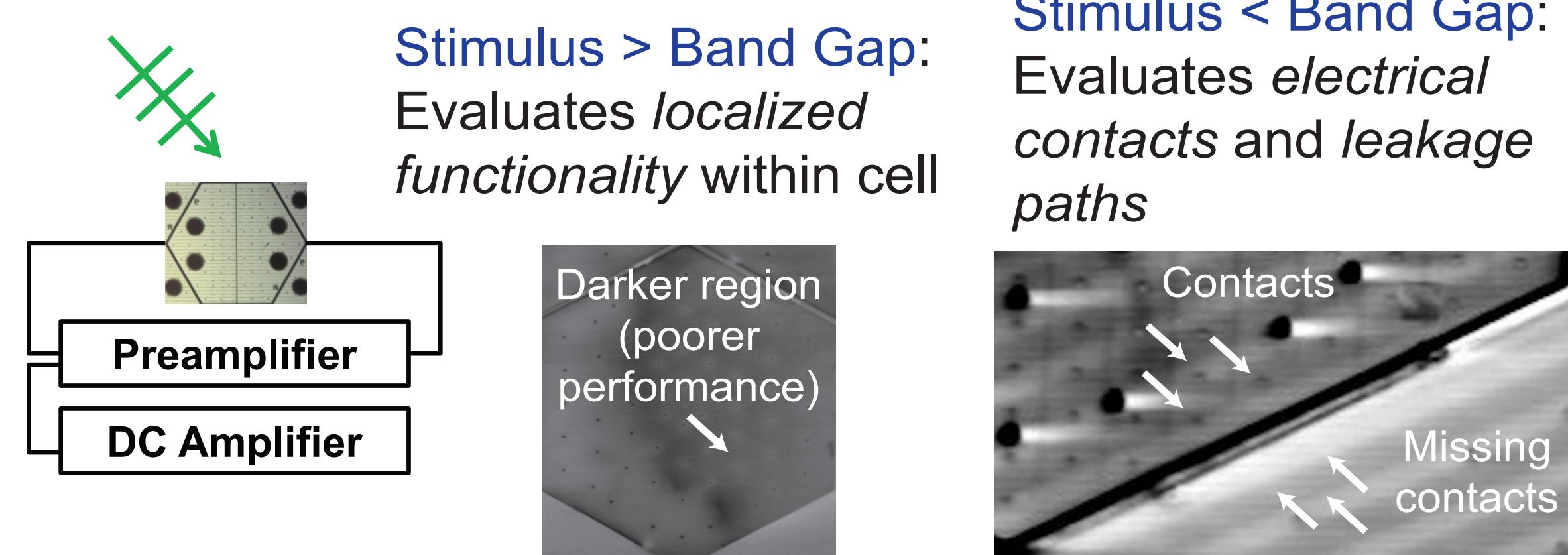
Failure Analysis Techniques

The following defect localization techniques were effective for MEPV:



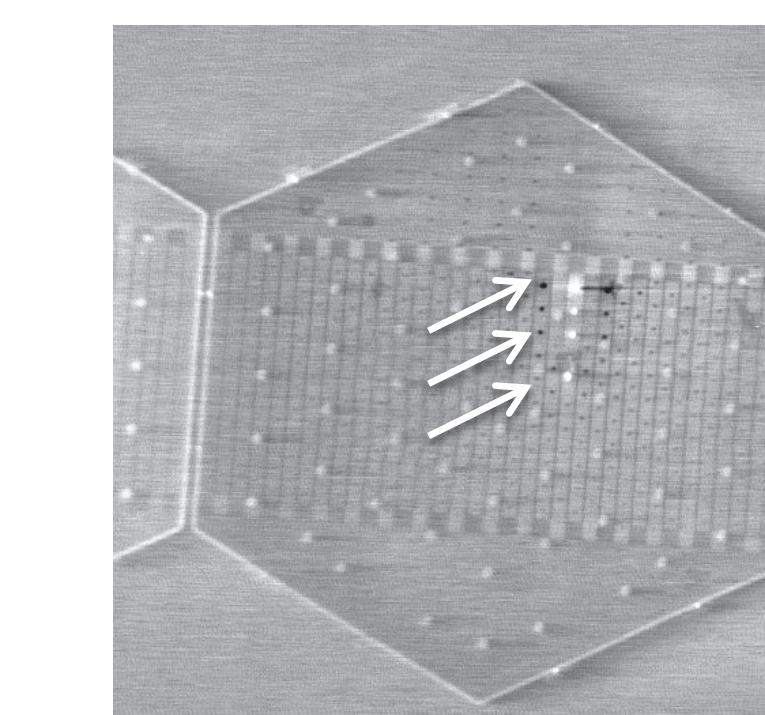
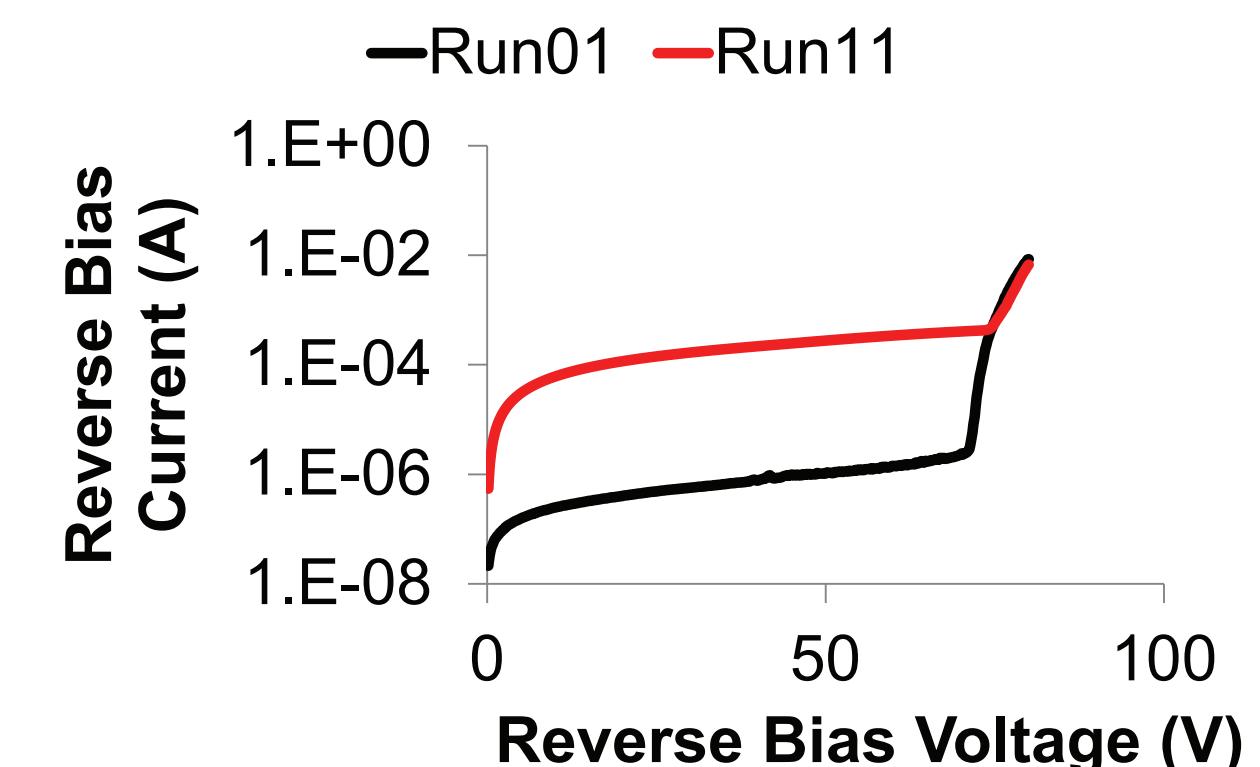
Optical Beam Induced Current (OBIC)

Discovered that DC amplification resulted in better performance than traditional AC filtering.



Reverse Bias Case Study

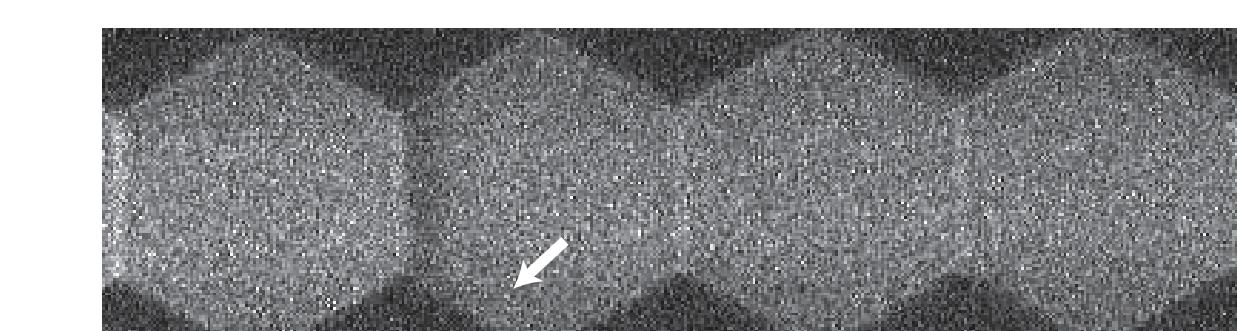
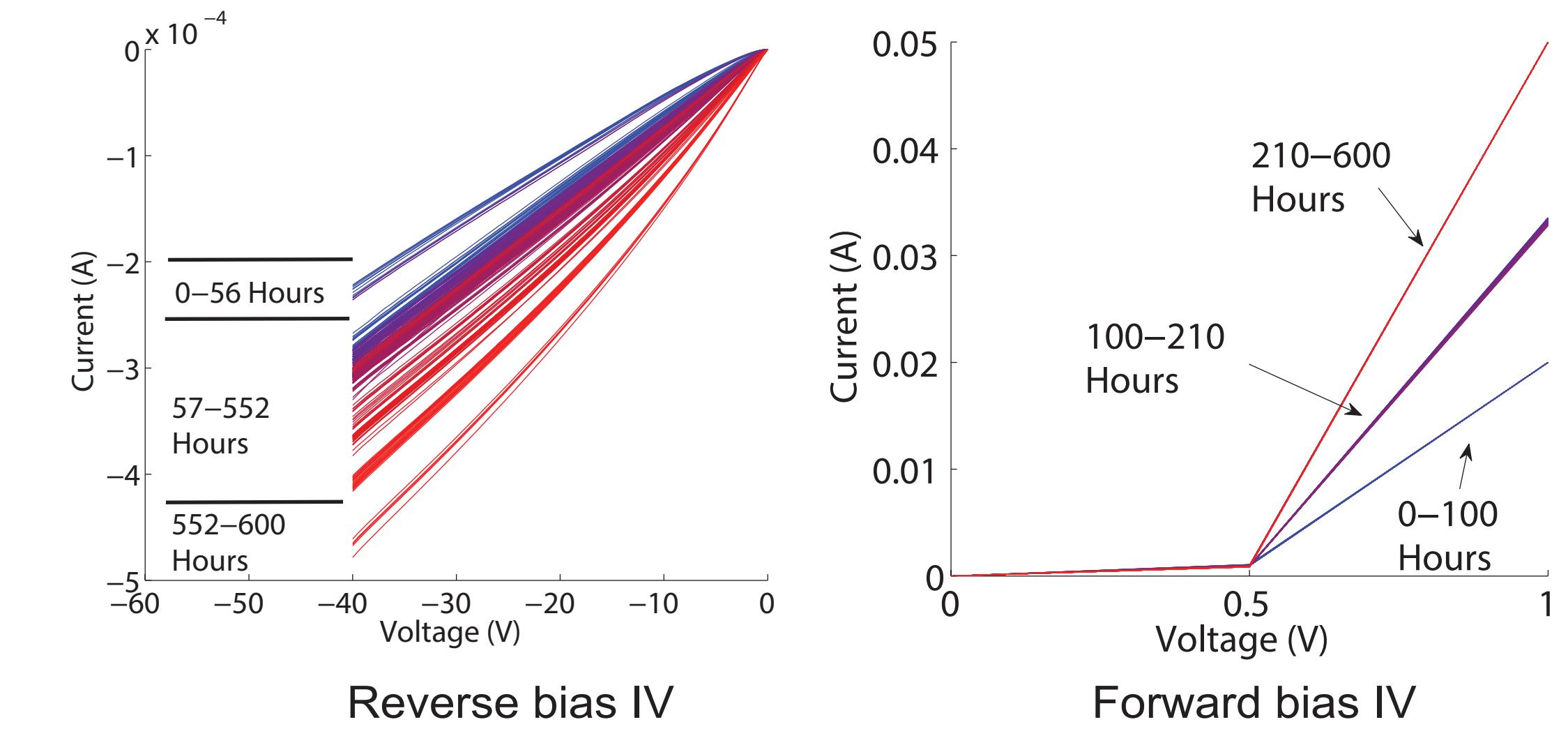
Found breakdown did not occur after > 10 reverse bias voltage sweeps up to 80V. Breakdown voltage found to be 75V.



Resulting leakage sites can be identified through below band gap OBIC.

Strong reverse bias EL signal suggests avalanche breakdown.

Repeated stress at lower voltages showed good resilience to reverse bias stress.



Each abrupt increase in forward bias current corresponds with new dark region under forward bias EL.

Summary

Microelectronic failure analysis techniques were successfully adapted for MEPV.

MEPV was demonstrated to have good robustness to reverse bias stress.